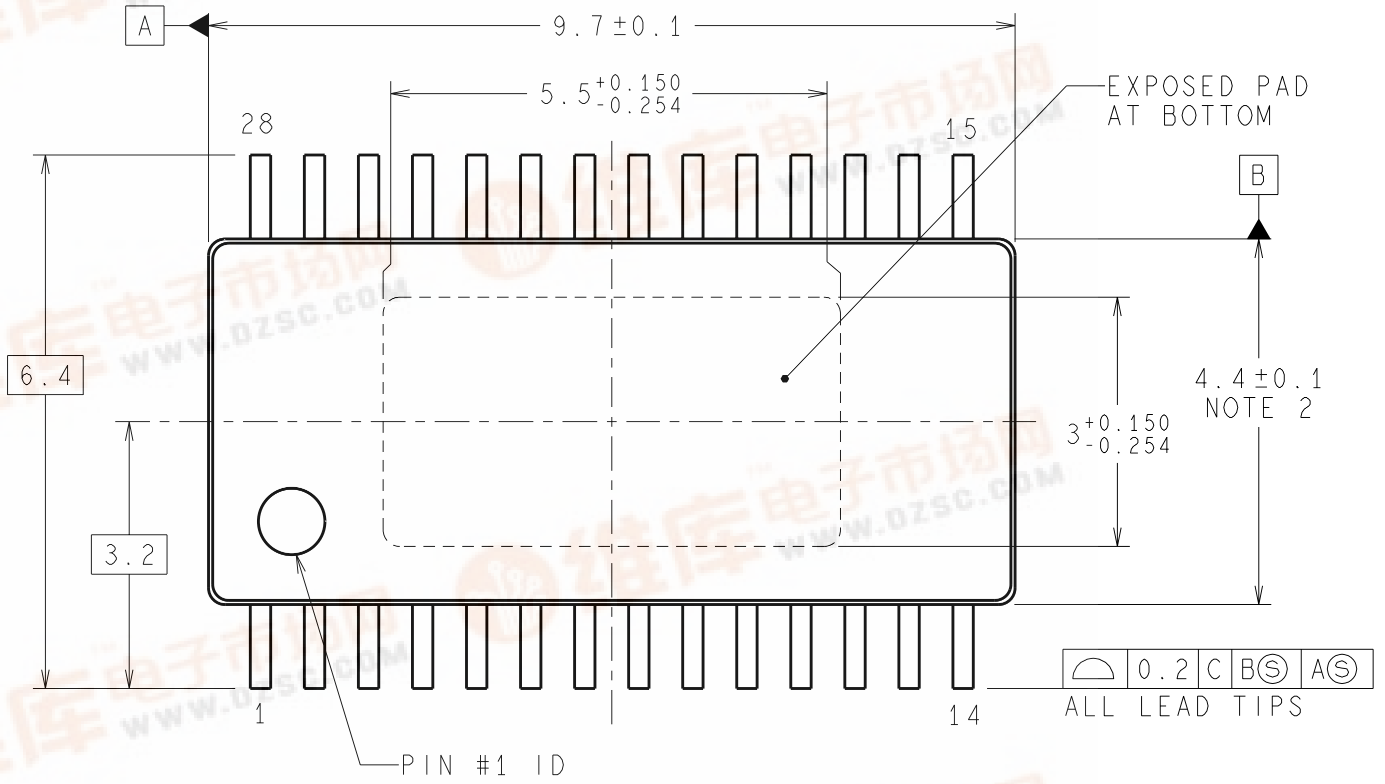
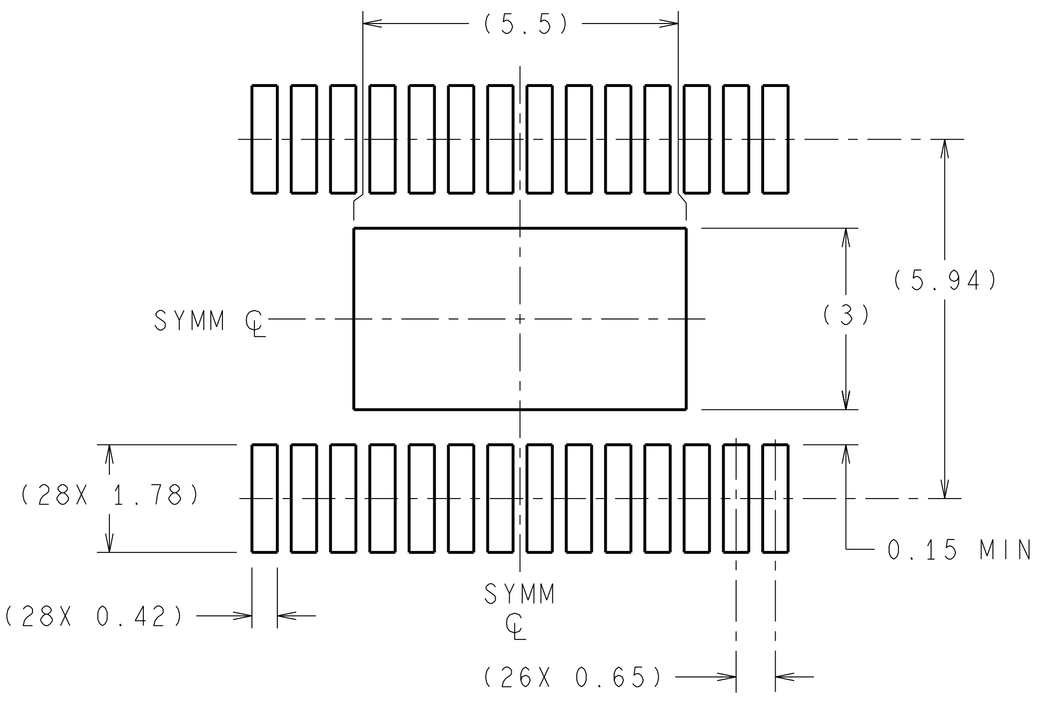
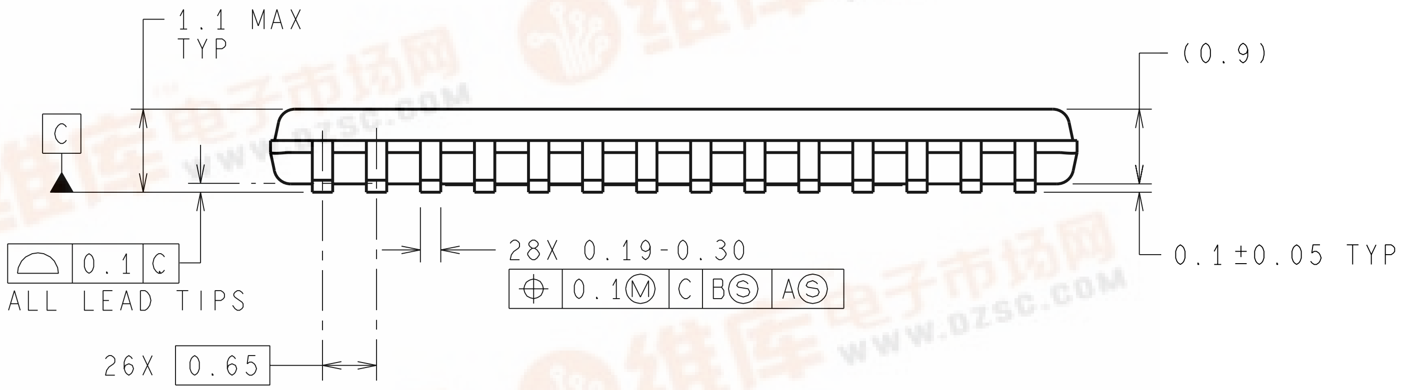
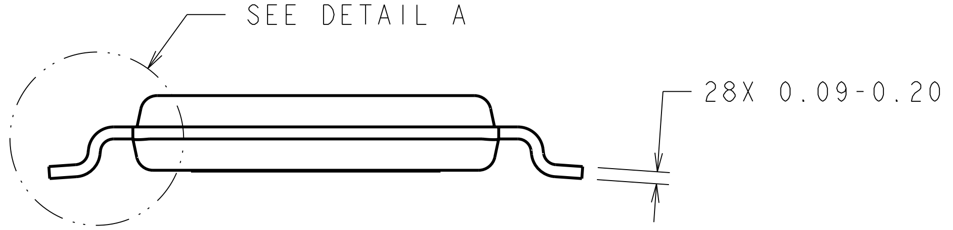
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11918	01/26/1998	MS/JB
B	EXT. PAD TOL'S WERE ±0.15	12098	09/16/1998	MS/JB
C	REVISE PER CURRENT STD; ADD SOLDER & MOLD FLASH NOTES; UPDATE TITLE; CHG DWG FORMAT TO B SIZE	1043	06/11/2003	TL/RW
D	RECOMENDED LAND PATTERN: DIM (5.5) WAS VARIABLE; ADD DIM (3).	1209	10/09/2003	MS/RW





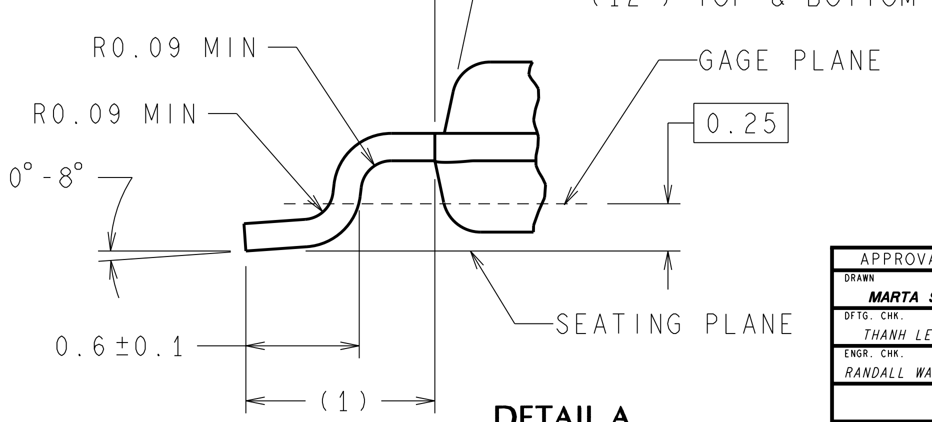
RECOMMENDED LAND PATTERN





DIMENSIONS ARE IN MILLIMETERS

DIMENSIONS IN ( ) FOR REFERENCE ONLY



DETAIL A
TYPICAL

NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
2. DIMENSION DOES NOT INCLUDE MOLD FLASH.
3. REFERENCE JEDEC REGISTRATION MO-153, VARIATION AET.

APPROVALS	DATE
DRAWN MARTA SUCHY	01/26/1998
DFTG. CHK. THANH LEQUANG	10/09/2003
ENGR. CHK. RANDALL WALBERG	10/09/2003

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

MOLDED TSSOP, JEDEC,
9.7x4.4x0.9mm BODY, 28 LD,
0.65mm PITCH, EXP PAD

PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	NTS	B	(SC)MKT-MXA28A	D